

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1076	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:23
L3	322	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:50
L4	870	polysilicon with polymer	USPAT	OR	ON	2008/12/30 13:55
L5	28	polysilicon with made with polymer	USPAT	OR	ON	2008/12/30 13:55
L6	968	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:08
L7	440	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:12
L8	14	polysilicon with part with polymer	USPAT	OR	ON	2008/12/30 14:13
L9	315	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:47
L10	13	(semiconductor or die or dice or chip or IC) and micro near cavity with MEMS	USPAT	OR	ON	2008/12/30 14:51

L11	2312	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:17
L12	1188	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:26
L13	92	polymer near polysilicon	USPAT	OR	ON	2008/12/30 16:07
L14	1293	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:14
S1	5	"5,477,008".pn. or "20040065932" or "20040028849"	US-PGPUB; USPAT	OR	OFF	2008/06/09 07:08
S2	20	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or hermetica\$3)	USPAT	OR	ON	2008/06/09 07:10
S3	18	("4838088" "5188983" "5589082" "5631428" "5668033" "5783749" "5937275" "5952572" "6133146" "6140144" "6232150" "6265246" "6297072" "6335224" "6635509").PN. OR ("6902656").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15

S4	7	("5025346" "5028983" "5454158" "5523619" "5686697" "5822856" "6178093").PN. OR ("6779247").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S5	40	("5589082" "5668033" "5783749" "5937275" "5952572" "6140144" "6232150" "6265246" "6297072" "6335224").PN. OR ("6635509").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S7	6	("5589082" "5963788" "6174820" "6429755" "6628177" "6635509").PN. OR ("7002436").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:23
S8	68	("4918032" "4997521").PN. OR ("5589082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:31
S11	194	("20010001931" "20010009110" "20010034076" "20020016058" "20020135047" "20040016989" "20040065932" "4665610" "4674319" "4766666" "4849071" "4945769" "4990462" "5075253" "5139624" "5156903" "5338416" "5445991" "5455547" "5461916" "5470797" "5491604" "5504026"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:41

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S12	1	"20070126068"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:52
S13	67	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:56
S14	1497	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:58
S15	1599	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:59
S16	1033	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:11
S17	424	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:28
S18	672	polysilicon with polymer	USPAT	OR	OFF	2008/06/09 08:34
S19	4	polysilicon with polymerized near material	USPAT	OR	OFF	2008/06/09 08:34
S20	27	polysilicon with polymerized	USPAT	OR	OFF	2008/06/09 08:35
S21	3437	polysilicon with glass	USPAT	OR	OFF	2008/06/09 08:38

S22	937	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:41
S23	315	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:49
S24	288	polysilicon near glass	USPAT	OR	OFF	2008/06/09 08:49
S25	5685	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:01
S26	301	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:25
S27	0	porous near silicon with photoresis	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40
S28	72	porous near silicon with photoresist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40
S29	2112	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:50
S30	1095	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:53

S31	0	photoresists with plug same micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S32	0	photoresists with plug and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S33	0	photoresists with (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S34	0	photoresists same (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S35	4008	photoresist with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59
S36	326	photoresist near material with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59
S37	1196	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 10:17
S38	798	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with polyimide	USPAT	OR	ON	2008/12/29 22:30
S39	32	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with polyimide and mems	USPAT	OR	ON	2008/12/29 22:30

S40	119	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S41	6051	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S42	1614	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:34
S43	4	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with (fill\$3 or seal \$3) with polyimide and mems	USPAT	OR	ON	2008/12/29 22:36
S44	1727	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:46

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